

## HCD Announces Volume Availability of 288MB SO-RIMM

SUNNYVALE, June 19, 2001 – High Connection Density (HCD) announced today the volume availability of 288MB SO-RIMM memory modules - the highest density SO-RIMM currently available on the market. The high density modules are available in ECC and non-ECC configurations and in various speed grades ranging from 600MHz to 800MHz, extending HCD's comprehensive SO-RIMM family line. The addition of the high density SO-RIMM to HCD's Module Product Line gives HCD the industry's most robust selection of RIMM offerings.

Prompted by feedback from networking OEMs seeking the high bandwidth, low pin-count of Rambus technology products within a standardized form factor, HCD's engineering team met the challenge with quick-turn design and prototyping, and state-of-the-art manufacturing capabilities. The high density SO-RIMM dimensionally conforms to the current SO-RIMM form factor, thus meeting component performance demands while addressing the space constrained needs of the networking markets. All of HCD's SO-RIMM products have passed the electrical validation process defined by Rambus Inc., which ensures that the SO-RIMM modules meet vigorous electrical parameters.

"Enabling the communications industry with high performance, cost effective and low form factor Rambus memories is an industry problem that HCD has demonstrated they can solve," stated Wade Appelman, Vice President of Advanced Networking Products at Vitesse Semiconductor Corporation. "HCD's continually expanding line of Rambus products supports our IQ2000™ family of network processors which is specifically designed to meet the high service and performance needs of networking and communications equipment."

"The 288MB SO-RIMM offers a high capacity memory solution to emerging markets in the networking and data storage spaces," said Ann Ciurczak, Product Manager for Standard Module Products at HCD. "We anticipate significant demand increases from these emerging markets in 2002."

### About High Connection Density Inc.:

High Connection Density Inc. (HCD) is a premier supplier of advanced memory modules and high performance modular subsystems. Focusing on modular solutions enabling the transition to next generation systems, HCD's expertise in packaging, thermal and mechanical design, and manufacturing position HCD to be a premier source of modular subsystems and solutions for high performance electronic applications. To learn more about HCD products and services, visit the website at [www.hcdcorp.com](http://www.hcdcorp.com).

### About Vitesse Semiconductor Corporation

Vitesse Semiconductor Corporation is a leading designer and supplier of innovative, high-performance integrated circuits (ICs) used in next generation networking and optical communications equipment. Vitesse is headquartered in Camarillo, Calif., and operates two fabrication facilities; one in Camarillo and one in Colorado Springs, Colo. Company and product information can be found on the web at [www.vitesse.com](http://www.vitesse.com) or is available by calling 1-800-VITESSE.